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Renesas Electronics Corporation

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HKT100***FL###

Precautions and Notes in Connection with Mounting
Paper Label-Type μ -Chip Inlet

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Note: "****" is a ROM code.

"###" is a specification code.

Note: " μ -Chip" and the μ -Chip Logo are either registered Trademarks or Trademarks of Hitachi,Ltd. in Japan and in other countries.

Section 1 Structure of Paper Label-Type μ -Chip Inlets

The paper label-type μ -Chip inlets consist of a label incorporating a COA-type inlet^{Note} and detachment paper.

Note: Please refer to the data sheet of individual product. (Document No.: REJ03P0003-0100 etc.)

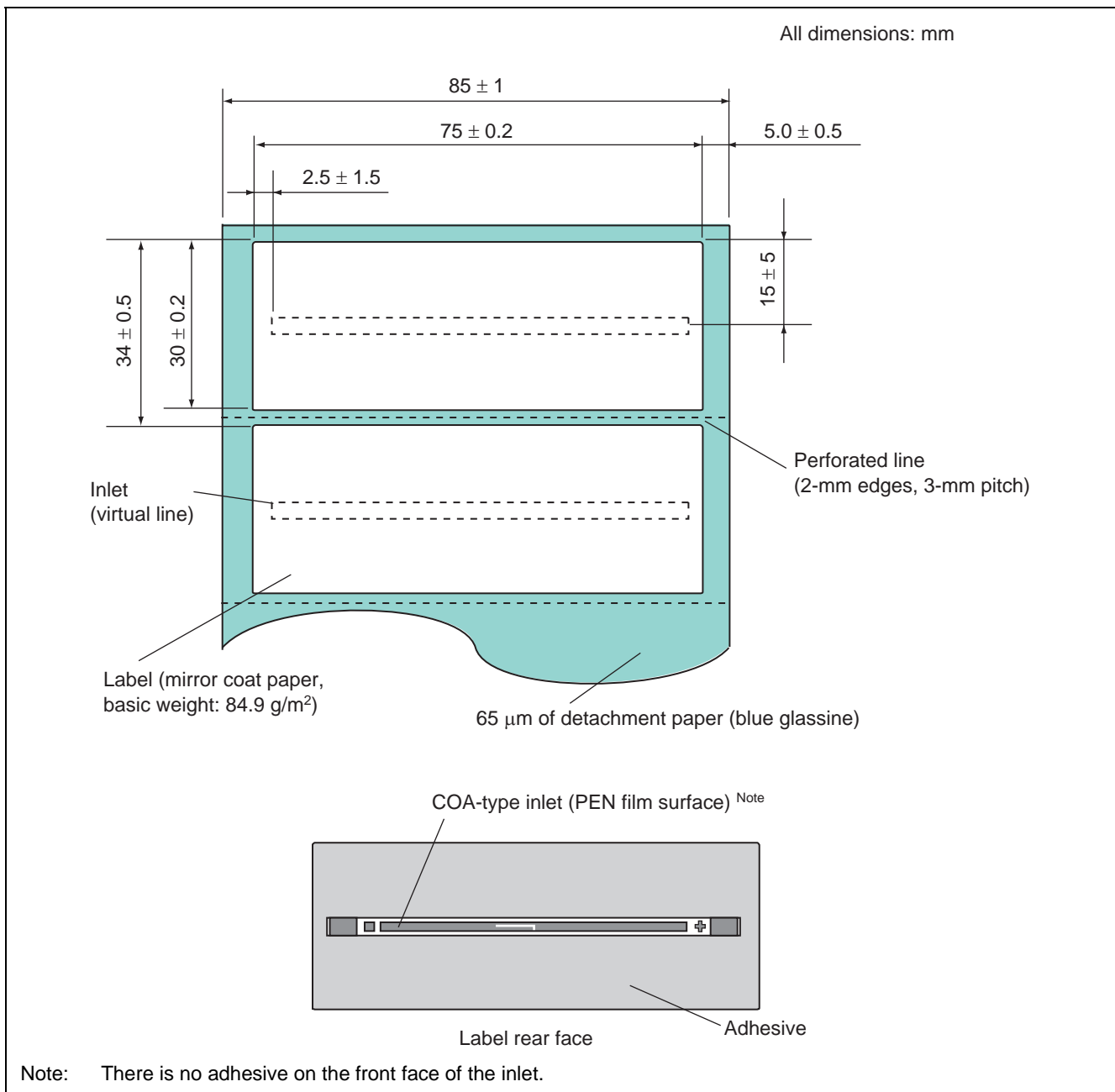


Figure 1 Structure of Paper Label-Type Inlet (Example of HKT100*FL001)**

Section 2 Measures Against Communication Errors Caused by Mechanical Stress or Attached Material

1. Deformation and disconnection of antenna

Since the RFID antenna module is thin, wires may be twisted or distorted when the label is attached.

This may lead to connection errors, and/or curving, breaking, or distortion after the product is on the market, which may lead to disconnections. Please conduct a thorough verification in each evaluation.

2. Cracks in the chip-mounting section

If the label is attached to the product using a label attachment device, mechanical stress may be concentrated on the chip-mounting section. This may create cracks in the resin or the chip. Therefore, please design a mounting method that avoids the use of impact stress by, for example, creating a slight depression in the part of the press or roller that comes in contact with the chip-mounting section. During evaluation, please verify that mechanical stress will not be applied to the chip-mounting section after the product goes on the market and is sold.

3. Communication errors caused by attached material

Depending on the material that is attached to the label, an RFID communication error may occur.

Please thoroughly verify this in your evaluation.

HKT100*FL### User's Manual**

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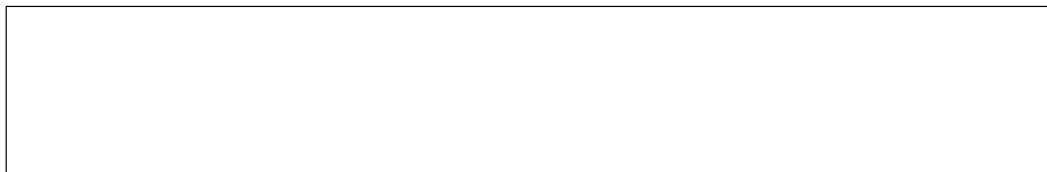
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